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Expedited Procedure
Examining Group 2829

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In rePATENT application of:

Art Unit:

2829

hunpei YAMAZAKI et al.

Examiner:

Evan T. PERT

TECHNOLOGY CENTER 2800

PATENT 740756-2101

Application No.: 09/502,675

Filed:

February 11, 2000

For:

SEMICONDUCTOR DEVICE AND)

METHOD OF MANUFACTURING

THEREFOR

may 13/03

AMENDMENT AFTER FINAL

Commissioner for Patents Washington, D.C. 20231

Dear Sir:

In response to the Examiner's Final Office Action mailed April 1, 2002, the period for responding having been extended two (2) months, please consider the following amendments and remarks in connection with the above-identified application.

IN THE CLAIMS:

Please cancel claim 2 without prejudice or disclaimer to the subject matter disclosed therein.

Please amend claims 1, 9, 18 and 27 as follows.

- 1. (Twice Amended) A semiconductor device comprising a driver circuit and a pixel section over a substrate, wherein:
- a) said driver circuit includes:

a first thin film transistor comprising:

a channel forming region and a third impurity region having n-type conductivity, wherein the channel forming region and the third impurity region are overlapped with a gate electrode; and

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